## **ON Semiconductor**



Title of Change:	NCV7381 Datasheet update – Revision 2
Effective date:	4 August 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <roman.buzas@onsemi.com></roman.buzas@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted.
Change category:	🗌 Wafer Fab Change 🗌 Assembly Change 🗌 Test Change 🔀 Other
Change Sub-Category(s): Manufacturing Site Change Manufacturing Process Cha	
Sites Affected:	applicable ON Semiconductor site(s) : External Foundry/Subcon site(s)
Description and Purpose: detailed description of the change and reason for the change.         Page 1: Quality statement updated         NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100         Qualified and PPAP Capable.         Page 16: Temperature Monitoring Parameters updated         Thermal shut-down level:         • Minimum: 150°C -> 155°C         • Maximum: 180°C -> 185°C	
This change increases the operating temperature range margin (which is positive from the application point of view) while it still keeps TSD level reasonably low to protect the device reliably in case of a failure.	
List of affected Standard Parts:	
NCV7381DP0G NCV7381DP0R2G	